

AMENDMENTS

IN THE SPECIFICATION

1) page 1, first paragraph, please replace this paragraph with the following:

a¹ This application is related to attorney docket number MEG01-001, filed on 01/16/01, serial number 09/760,909, assigned to a common assignee.

2) page 12, last paragraph, page 13, please replace this paragraph with the following:

a² Contact pads, having dimensions of about between about 60 x 60 μm and 120 x 120 μm , are in current practice frequently used as access or input/output contact points during wafer level testing of semiconductor devices. In view of the complexity and density of high performance semiconductor devices, these contact pads will, during a complete cycle of testing, be contacted a number of times. Testing is as a matter of economic necessity performed at high speed, which frequently results in landing the test probe on the surface of the contact pad at high speed,